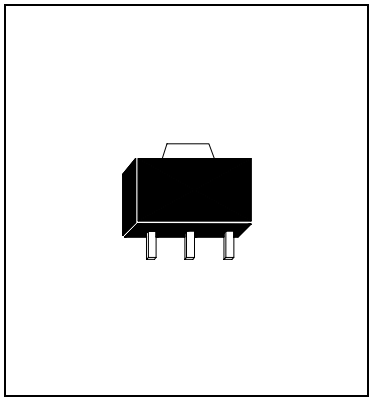
HM3906

PNP EPITAXIAL PLANAR TRANSISTOR



Description

The HM3906 is designed for general purpose switching and amplifier applications.

Absolute Maximum Ratings

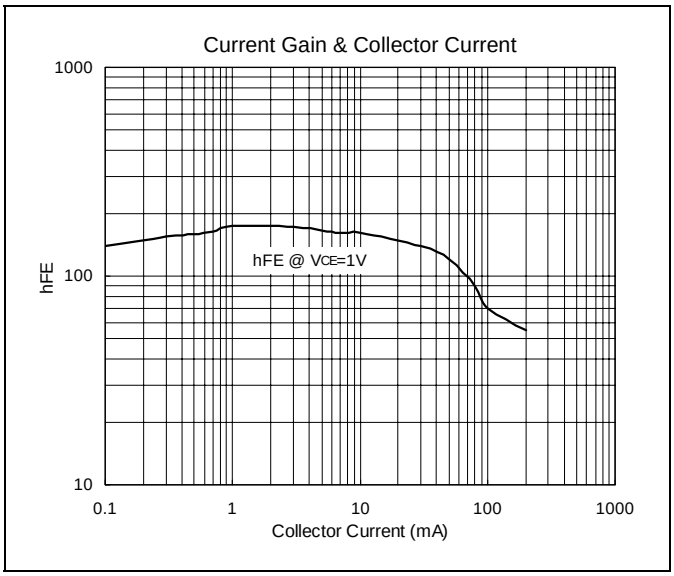
- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 1 W
- Maximum Voltages and Currents (Ta=25°C)
  VCBO Collector to Base Voltage ..... -40 V
  VCEO Collector to Emitter Voltage ..... -40 V
  VEBO Emitter to Base Voltage ..... -5 V
  IC Collector Current ..... -200 mA

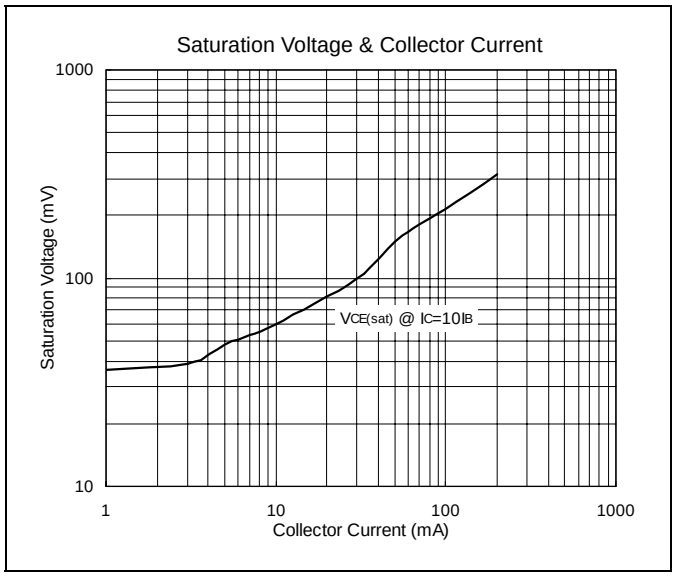
Characteristics (Ta=25°C)

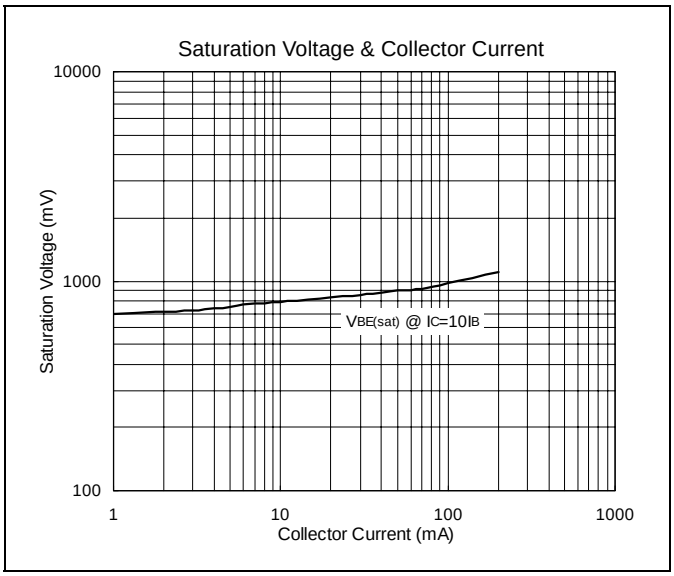
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-40	-	-	V	IC=-100uA
BVCEO	-40	-	-	V	IC=-1mA
BVEBO	-5	-	-	V	IE=-10uA
ICEX	-	-	-50	nA	VCE=-30V, VBE=-3V
*VCE(sat)1	-	-	-250	mV	IC=-10mA, IB=-1mA
*VCE(sat)2	-	-	-400	mV	IC=-50mA, IB=-5mA
*VBE(sat)1	-650	-	-850	mV	IC=-10mA, IB=-1mA
*VBE(sat)2	-	-	-950	mV	IC=-50mA, IB=-5mA
*hFE1	60	-	-		VCE=-1V, IC=-100uA
*hFE2	80	-	-		VCE=-1V, IC=-1mA
*hFE3	100	-	300		VCE=-1V, IC=-10mA
*hFE4	60	-	-		VCE=-1V, IC=-50mA
*hFE5	30	-	-		VCE=-1V, IC=-100mA
fT	250	-	-	MHz	VCE=-20V, IC=-10mA, f=100MHz
Cob	-	-	4.5	pF	VCB=-5V, f=1MHz

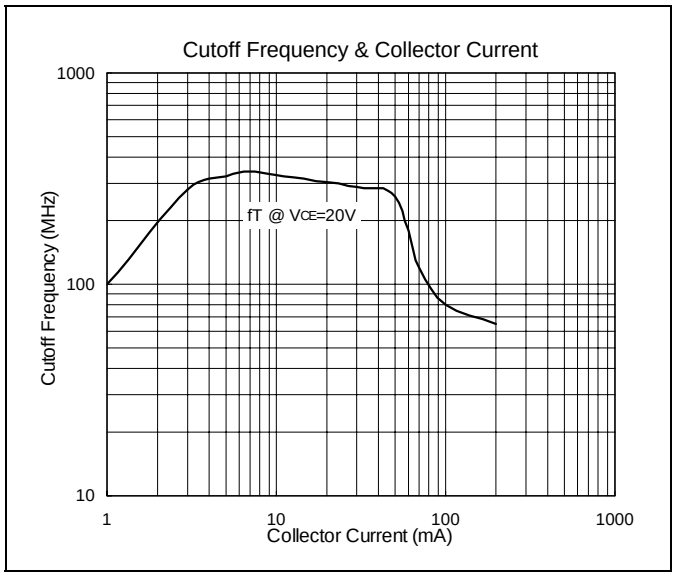
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

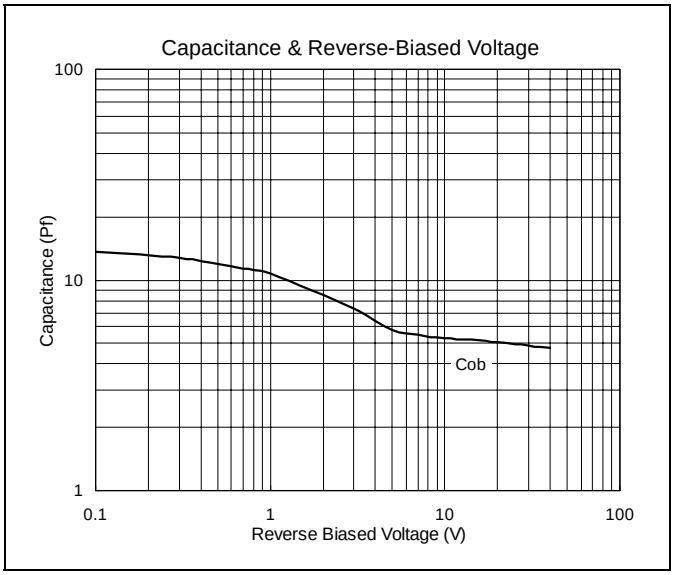
Characteristics Curve

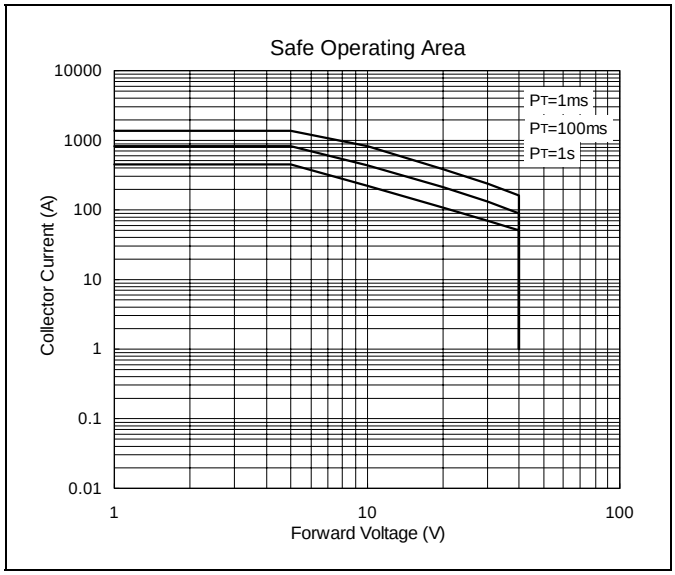




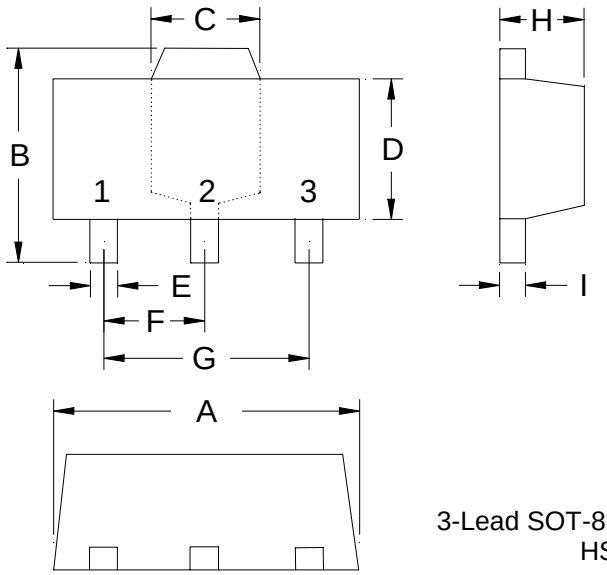




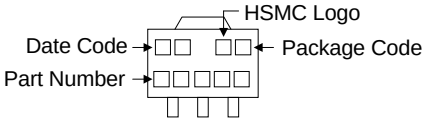




SOT-89 Dimension



Marking :



Style : Pin 1.Base 2.Emitter 3.Collector

3-Lead SOT-89 Plastic Surface Mounted Package
HSMC Package Code : M

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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